## AMENDMENTS TO THE CLAIMS

**Listing of Claims -** This will replace all prior listings of claims in the application:

1. (Withdrawn) A socket contact, comprising:

a first end, the first end having a simple geometry that is configured to interconnect with a load-generating device; and

a second end, the second end having a contact pad of a complex geometry that is configured to enable placement and electrical coupling of a component between the socket contact and a substrate.

2. (Withdrawn) The socket contact of Claim 1, wherein the contact pad includes a first contact pad area and a second contact pad area.

3. (Withdrawn) The socket of Claim 2, wherein the second contact pad area is rectilinear and the first contact pad area is curvilinear.

4. (Withdrawn) The socket of Claim 2, wherein the first contact pad area is configured to couple to an interface configuration selected from a group including LGA, PGA, CSP, and BGA.

5. (Withdrawn) The socket of Claim 2, wherein the second contact pad area extends in a third dimension from the first contact pad area.

6. (Withdrawn) The socket of Claim 5, wherein the second contact pad area includes a pair of opposed contact pad areas configured to grippingly engage a component.

7. (Withdrawn) The socket of Claim 1, wherein the component is selected from a group including capacitors, resistors, diodes, and inductors.

8. (Withdrawn) The socket contact of Claim 1, wherein a plurality of socket contacts are electrically and mechanically interconnected with each other.

9. (Original) A system, comprising:

a system substrate;

a bus disposed on the system substrate to facilitate data exchange;

a memory configured to store data, the memory disposed on the system substrate and coupled to the bus; and

a socket coupled to the system substrate, the socket including:

a body;

a socket contact housed by the body, the socket contact including

a first end, the first end having a simple geometry that is configured to interconnect with a load generating device; and

a second end, the second end having a contact pad of a complex geometry that is configured to enable placement and electrical coupling of a component between the socket contact and a substrate.

10. (Original) The system of Claim 9, wherein the contact pad includes a first contact pad area and a second contact pad area.

11. (Original) The system of Claim 10, wherein the second contact pad area is rectilinear, and the first contact pad area is curvilinear.

12. (Original) The system of Claim 10 wherein the first contact pad area is configured to couple to an interface configuration is selected from a group including LGA, PGA, CSP, and BGA.

13. (Original) The system of Claim 10, wherein the second contact pad area extends in a third dimension from the first contact pad area.

14. (Original) The system of Claim 13, wherein the second contact pad area includes a pair of opposed contact pad areas configured to grippingly engage a component.

15. (Original) The system of Claim 9, wherein the component is selected from a group including capacitors, resistors, diodes, and inductors.

16. (Original) The system of Claim 9, wherein a plurality of socket contacts are electrically and mechanically interconnected with each other.

17. (Original) A socket connection, comprising:

a substrate;

a component, the component electrically coupled to the substrate; and

a socket body, the socket body including a plurality of socket contacts, each of the socket contacts including

a first end configured to electrically couple with a load generating device, and

a second end, the second end having a contact pad configured to enable placement and electrical coupling of the component between the contact second end and the substrate.

18. (Original) The socket connection of Claim 17, wherein the first end is of a simple

geometry and the second end is of a complex geometry.

19. (Original) The socket connection of Claim 17, wherein the component is selected from a group including capacitors, resistors, diodes, and inductors.

20. - 23. (Withdrawn)